



PRINTED CIRCUIT BOARDS
INTERCONNECTION CARRIERS

State of the Art: PCB's

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Datum:

Seite:

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01

4.11.2001

1/1

Schematic Key for Multilayer and HDI-Technology Build-Ups

| a | b | c | d | e | f | g + h + i |
|---|---|---|---|---|---|-----------|
|---|---|---|---|---|---|-----------|

04 236 FR4 35 L150.35 P18

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

04_236_FR4_35_L150.35_p18

| Layers | in μ | Material | Build-Up | Assembly | |
|-----------------|------------|----------|----------|----------|--------------------------------|
| Layer-1 | 35 μ | Copper | | A1 B | |
| | 180 μ | Prepreg | | | (180 μ PrePreg-Type: 7628) |
| | 180 μ | Prepreg | | | |
| Layer-2 | 35 μ | Copper | | | |
| | 1500 μ | L-FR4 | | | |
| Layer-3 | 35 μ | Copper | | | |
| | 180 μ | Prepreg | | | |
| | 180 μ | Prepreg | | | |
| Layer-99 | 35 μ | Copper | | | |

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